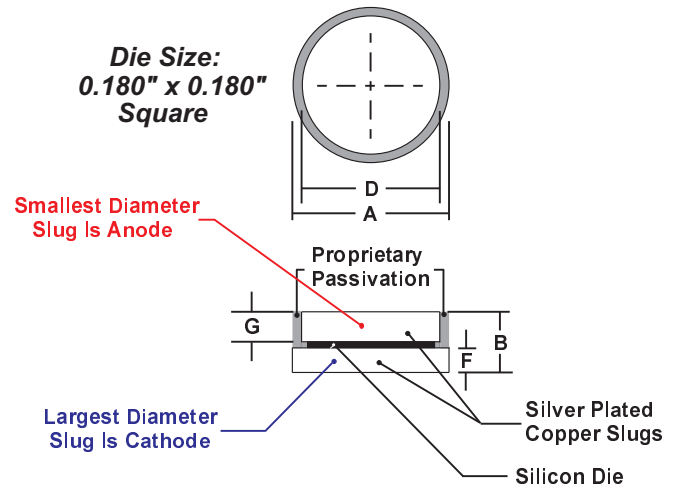


50 AMP JUMBO DIODE CELL

FEATURES

- Void Free Vacuum Die Soldering For Maximum Mechanical Strength and Heat Dissipation (Solder Voids: Typical < 2%, Max. < 10% of Die Area)
- Biggest Effective Die Area for the 50 Amp Class of Jumbo Diode Cells
- High Temperature Solder (Solidus 287°C, Liquidus 296°C) to Allow Higher Operating And Assembly Temperatures
- Copper Headers Are Silver Plated For Easy Soldering And Superior Solder Joints
- Largest Diameter Header Is Cathode

MECHANICAL SPECIFICATION



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.25	7.35	0.285	0.290
B	2.05	2.15	0.080	0.085
D	6.50	6.60	0.256	0.260
F	0.72	0.82	0.028	0.032
G	0.96	1.07	0.038	0.042

RoHS COMPLIANT

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS							UNITS
		BAR 5001D	BAR 5002D	BAR 5004D	BAR 5006D	BAR 5008D	BAR 5010D	BAR 5012D	
Series Number									
Maximum DC Blocking Voltage	VRRM	100	200	400	600	800	1000	1200	VOLTS
Maximum RMS Voltage	VRMS	70	140	280	420	560	700	840	
Maximum Peak Recurrent Reverse Voltage	VRRM	100	200	400	600	800	1000	1200	
Average Forward Rectified Current @ Tc=125 °C	IO	50							AMPS
Peak Forward Surge Current (8.3mS single half sine wave superimposed on rated load)	IFSM	600							
Maximum Forward Voltage Drop at 50 Amps DC	VFM	1.1 (1.05 Typical)					1.15		VOLTS
Maximum Average DC Reverse Current @ TA = 25 °C	IRM	2							µA
At Rated DC Blocking Voltage @ TA = 125 °C		50							
Maximum Thermal Resistance, Junction to Case (Note 1)	RθJC	0.8							°C/W
Junction Operating and Storage Temperature Range	TJ, TSTG	-65 to +175							°C

Notes: 1) Single Side Cooled

BAR504